

## SMA Plastic-Encapsulate Diodes

### Fast Recovery Rectifier Diodes

#### Features:

- $I_{F(AV)}$  3A
- $V_{RRM}$  50V-1000V
- High surge current capability
- Polarity: Color band denotes cathode

#### Applications:

- Rectifier

#### Marking

- RS3X

X : From A To M

SMA



### Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	RS3						
				A	B	D	G	J	K	M
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	$V_{RMS}$	V		35	70	140	280	420	560	700
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave , Resistance load , $T_L=110^{\circ}C$	3.0						
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	60Hz Half-sine wave , 1 cycle , $T_a=25^{\circ}C$	100						
Operation Junction and Storage Temperature Range	$T_J, T_{STG}$	$^{\circ}C$		-55 ~ +150						

### Electrical Characteristics (T=25°C Unless otherwise specified)

Item	Symbol	Unit	Test Condition	RS3						
				A	B	D	G	J	K	M
Peak Forward Voltage	$V_F$	V	$I_F=3.0A$	1.3						
Maximum reverse recovery time	$t_{rr}$	ns	$I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$	150			250		500	
Peak Reverse Current	$I_{RRM1}$	$\mu A$	$V_{RM}=V_{RRM}$	$T_a=25^{\circ}C$						
	$I_{RRM2}$			$T_a=100^{\circ}C$						
Thermal Resistance(Typical)	$R_{\theta J-A}$	$^{\circ}C/W$	Between junction and ambient	50						
	$R_{\theta J-L}$		Between junction and terminal	15						

#### Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.27" x 0.27" (7.0 mm x 7.0 mm) copper pad areas

**Typical Characteristics**

FIG.1: FORWARD CURRENT DERATING CURVE

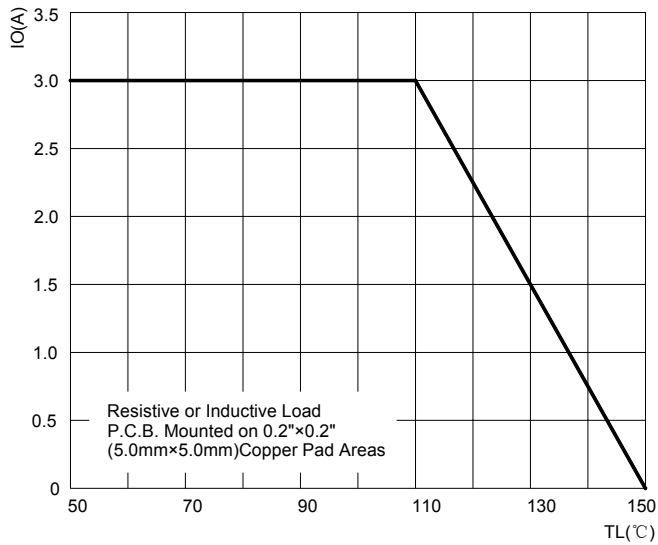


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

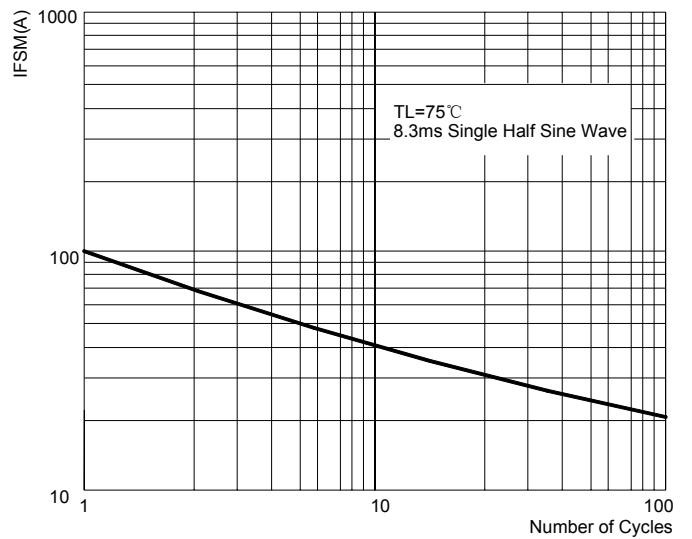


FIG.3: TYPICAL FORWARD CHARACTERISTICS

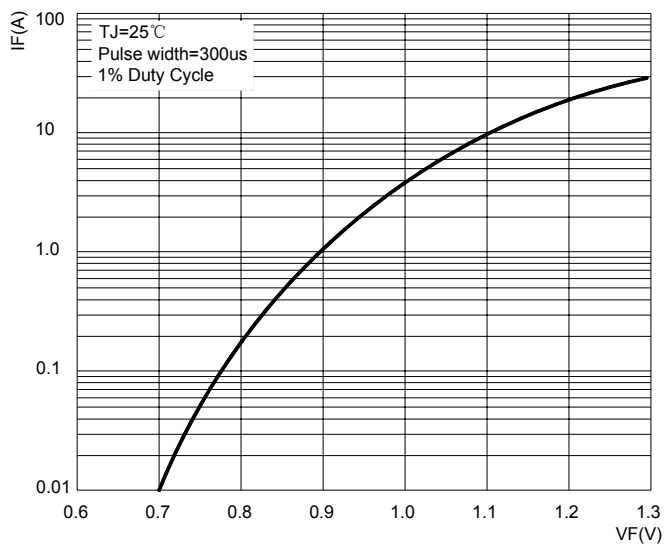


FIG.4: TYPICAL REVERSE CHARACTERISTICS

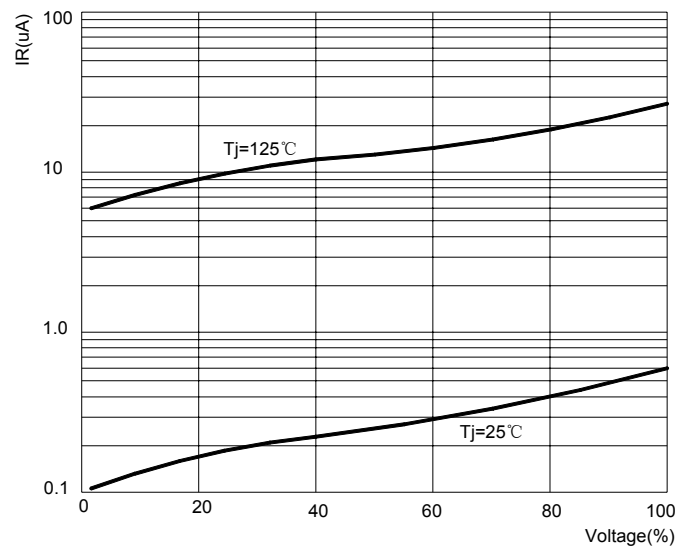
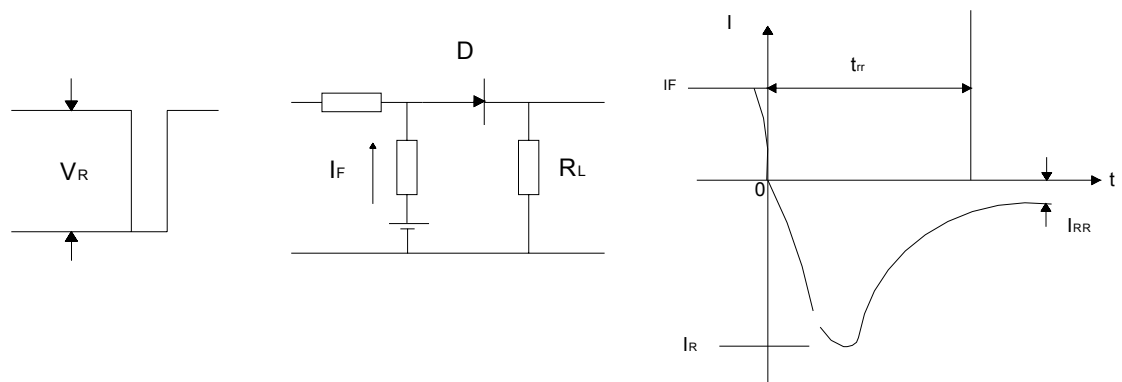
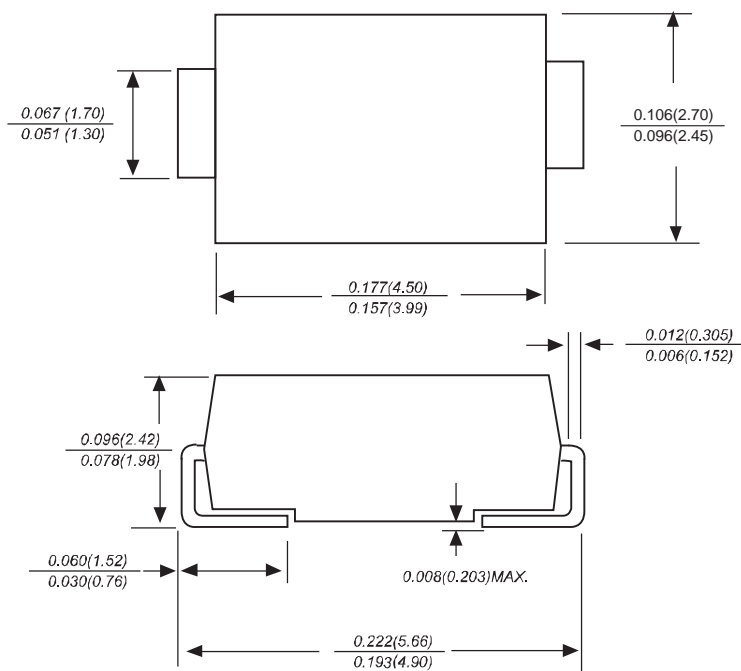


FIG.5: Diagram of circuit and Testing wave form of reverse recovery time

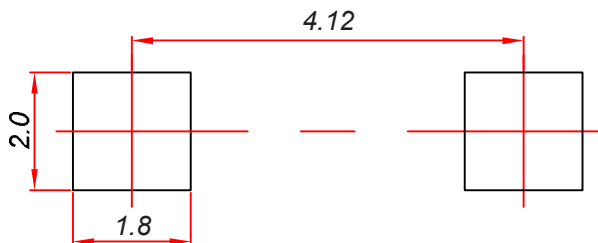


### SMA Package Outline Dimensions



Dimensions in inches and (millimeters)

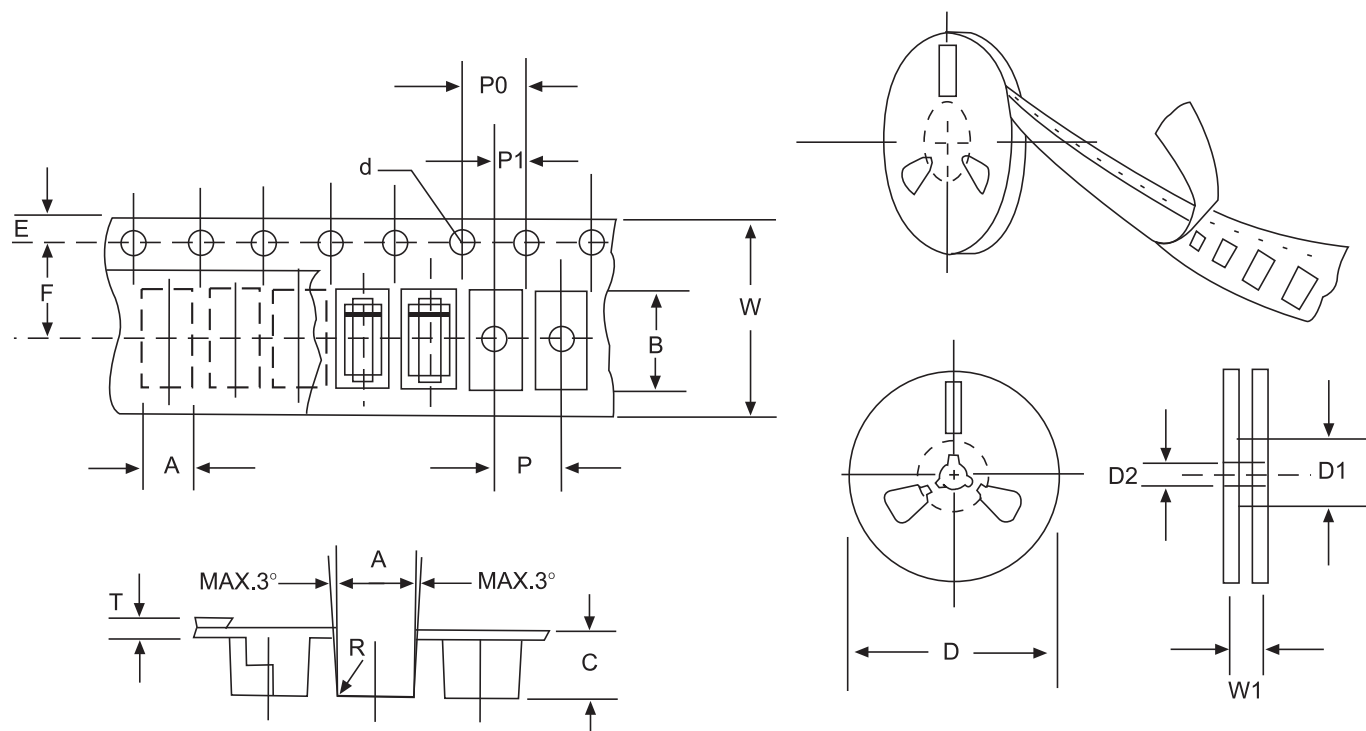
### SMA Suggested Pad Layout



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$ mm.
3. The pad layout is for reference purposes only.

**Reel Taping Specifications For Surface Mount Devices- SMA**



**FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING**

ITEM	SYMBOL	SMA mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11 ± 0.079)
Reel inner diameter	D1	75 ±1.0 ( 2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Stroket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.28±0.02(0.011 ±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.